# Product End-of-Life Disassembly Instructions

## Product Category: Notebooks and Tablet PCs

### Marketing Name / Model
[List multiple models if applicable.]

- HP Envy 17 3D
- Name / Model #2
- Name / Model #3
- Name / Model #4
- Name / Model #5

### Purpose:
The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies</td>
<td>With a surface greater than 10 sq cm (Motherboard, usb board, wireless card)</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries (Battery, RTC Battery)</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps (LCD panel)</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances | 0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Screwdriver</td>
<td>Type-cross #1 (JIS B 4633-1987)</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disassemble Main Battery
2. Disassemble Rubber feet*4
3. Disassemble HDD/RAM Door
4. Remove Ram/HDD-Door
5. Dis-fasten KB screw on battery housion(M2.5*4*3pcs).
6. Dis-fasten Base/Top screw on battery housion(M2.5*4*3pcs).
7. Dis-fasten Base/Top screw on base bottom (M2.5*6.5*9pcs).
8. Pull out Keyboard membrane and Disassemble keyboard.
9. Dis-fasten Top/Base screw on top side(keyboard region)(M2.5*4*2pcs)
10. Pull out Touchpad FFC and power FFC.
12. Disassemble TP module
13. Pull out WLAN cable
14. Pull out LCD cable from MPCB
15. Pull out BT cable from MPCB
16. Dis-fasten Hinge/Base screws(M2.5*6.5*4pcs)
17. Remove LCD module
18. Pull out HDD cable
19. Dis-fasten second HDD/Base screws(M2.5*4*4pcs)
20. Remove main HDD and second HDD.
21. Dis-fasten screw on ODD Bracket(M2.5*4*3pcs).
22. Remove ODD.
23. Dis-fasten screw on Motherboard(M2.5*4*2pcs).
24. Disassemble Motherboard.
25. Dis-fasten Thermal Module screws(VGA/CPU) from MB.
27. Dis-fasten Speaker/Woofer screws(M2.5*4*4pcs-->speaker,M2.5*4*3pcs-->woofer)
28. Remove Speaker/woofer.
29. Remove usb FFC.
30. Dis-fasten daughter board(USB) screw(M2.5*4*2pcs)
31. Remove daughter board(USB).
32. Dis-fasten WLAN/MPCB screw(M2.5*4*2pcs)
33. Remove WLAN card
34. Disassemble LCD-Bezel(with PMMA)/Cover (M2.5*5*4pcs)
35. Dis-fasten LCD-BKT screws on lcd bezel(M2.5*5*8pcs)
36. Disassemble camera module and BT module/Connector
37. Remove camera and BT module.
38. Dis-fasten LCD-BKT/Panel screws (M2*2.5*4pcs)
39. Remove Panel with LCD-BKT
40. Remove LCD-cable from Panel connector
41. Remove Panel
42.
43.
44.
45.
46.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
None.
**Standard Operating Procedure**

<table>
<thead>
<tr>
<th>MODEL</th>
<th>LP156WF1-TLE1</th>
</tr>
</thead>
<tbody>
<tr>
<td>Purpose</td>
<td>LCM Disassembly Method</td>
</tr>
<tr>
<td>Issued date</td>
<td>2009.9.10</td>
</tr>
<tr>
<td>Dep.</td>
<td>NB Qualification Team</td>
</tr>
</tbody>
</table>

**Prepared by**
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**STEP 1** Remove Side Tape & Bottom Tape

**STEP 2** Remove PCB Cover Shield
**STEP 3** Separate FPC from PCB

**STEP 4** Separate Metal Chassis from Plastic Frame (From Bottom Hook to Left/Right Hook)
STEP 5  Separate Panel Assembly from Backlight Unit